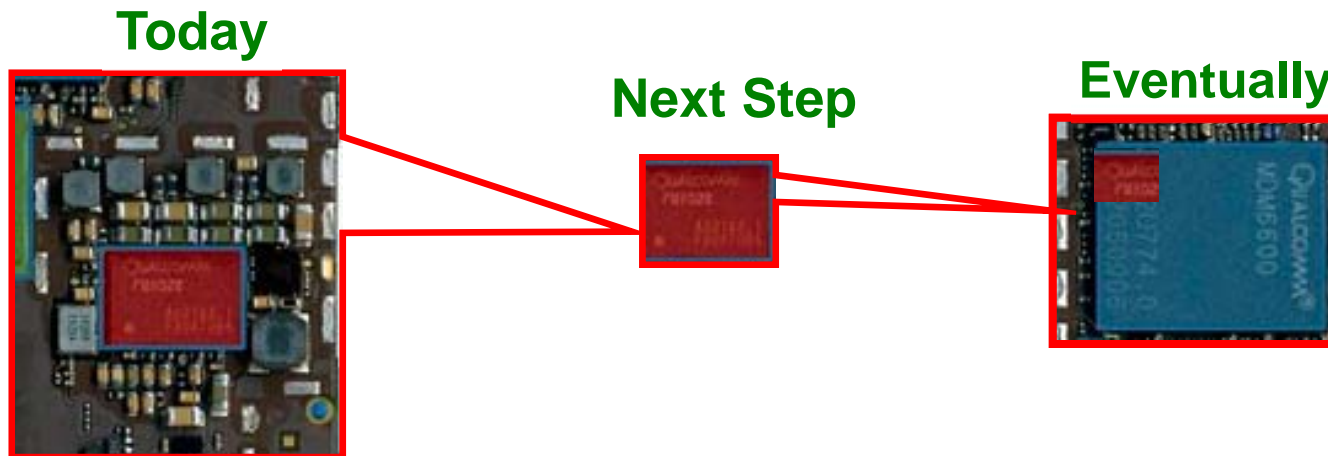


The Road to Integrated Power Conversion via the Switched Capacitor Approach

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EECS Department, UC Berkeley

Integrated Power

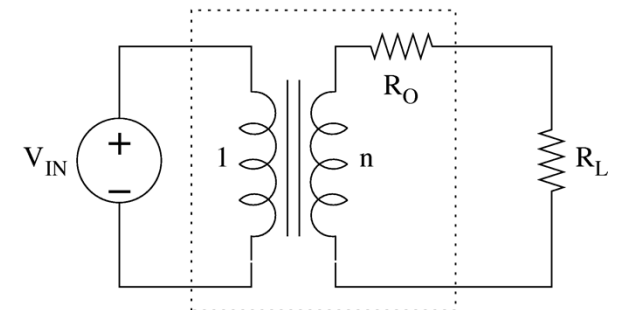
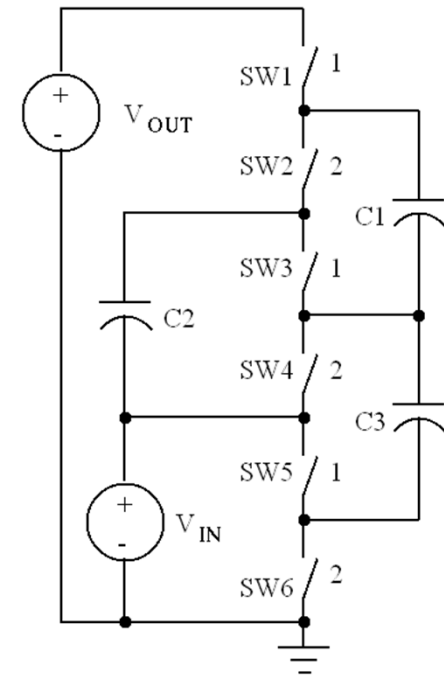
- **Integration has benefits:**
 - Reduce passives -> save board real estate, passive cost
 - More voltage domains on-die, improve efficiency in multi-core processor
 - Efficiency + fine-grain power management -> **battery life**
- **and challenges:**
 - Aim for $\sim 10\text{W}/\text{mm}^2$
 - Wide input range: eg. Li-type battery voltage discharge range
 - Limited on-die resources in standard CMOS
 - Efficiency over wide load voltage and current range
 - Ultra-low-power modes



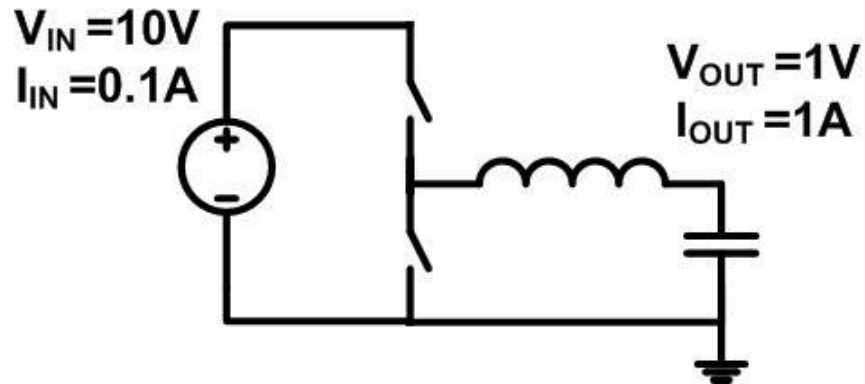
> 25% board area

Switched Capacitor Power Converters

- Only switches and capacitors
- Can support multiple input or output voltages/terminals
- Simple full integration in standard process
- Works well over a wide power range
 - Single mode, can adjust clock rate
 - No minimum load
- No inductive switching losses
- Stacked devices enable high voltage with low voltage processes
- Simple low freq model as an ideal transformer with Thevenin impedance
 - freq dependent loss and leakage

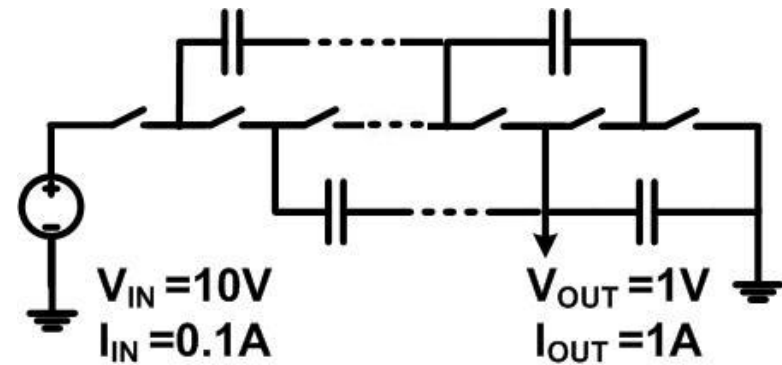


First Look



Magnetic boost/buck:

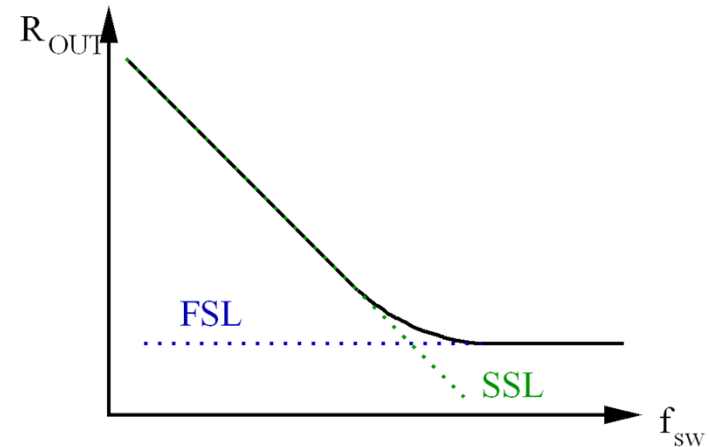
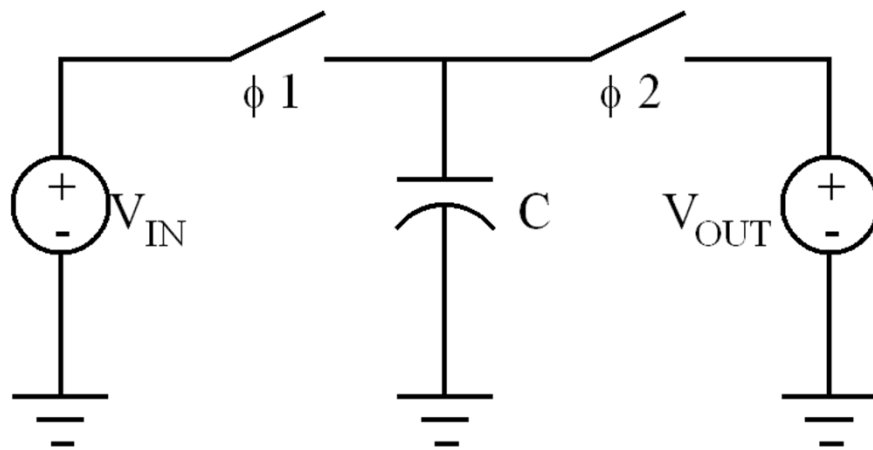
- 10-to-1 V conversion, 1A @ 1V
- S1, S2 rated for V-A product of $V \cdot I = 10 \text{ V-A}$
- Sum up to 20 V-A
- Need inductor, inductor loss, Inductive switching



10-to-1 Ladder Switched-Cap:

- 10-to-1 V conversion, 1A @ 1V
- 20 switches, each blocks 1V
- 18 switches handle $1/5 \text{ A}$
- 2 switches handle $9/5 \text{ A}$
- V-A product sums up to $36/5 = 7.2 \text{ V-A}$
- Intrinsic CMOS device convenient

SC Analysis: Simplest Example



- Slow Switching Limit (SSL):
 - Impulsive currents (charge transfers)
 - Resistance negligible (assume $R = 0$)
 - This (SSL) impedance is the switching loss!
- Fast Switching Limit (FSL):
 - Constant current through switches
 - Model capacitors as voltage sources ($C \rightarrow \infty$)

$$i = f_{sw} \Delta q = f_{sw} C \Delta v$$

$$i = \frac{1}{4} \frac{1}{R} \Delta v$$

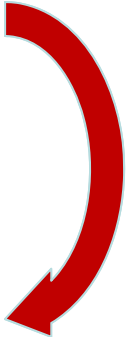
$$(\Delta v = V_{IN} - V_{OUT})$$

Why Not S-C ?

- Difficult regulation?
- Interconnect difficulty for many caps?
- Voltage rating of CMOS processes?
- Magnetic-based ckts = higher performance?
- Ripple?
- Fundamental charge sharing losses?

Discrete Inductors vs. Discrete Capacitors

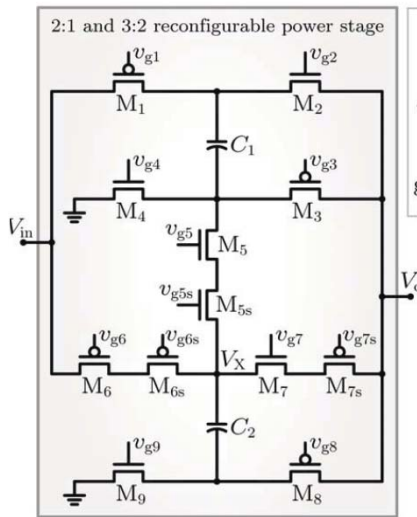
Type	Manufacturer	Capacitance	Dimension	Energy Density
Ceramic Cap	Taiyo-Yuden	22μF @4V	1.6 x 0.8 x 0.8	344
Ceramic Cap	Taiyo-Yuden	1μF@35V	1.6 x 0.8 x 0.8	1196
Tantalum Cap	Vishay	10μF@4V	1.0 x 0.5 x 0.6	533
Tantalum Cap	Vishay	100μF@6.3V	2.4 x 1.45 x 1.1	1037
Electrolytic Cap	Kemet	22μF@16V	7.3 x 4.3 x 1.9	94
Electrolytic Cap	C.D.E	210mF@50V	76φ x 219	172
Shielded SMT Inductor	Coilcraft	10μH @ 0.21A	2.6 x 2.1 x 1.8	0.045
Shielded SMT Inductor	Coilcraft	100μH @ 0.1A	3.4 x 3.0 x 2.0	0.049
Shielded inductor	Coilcraft	170μH @ 1.0A	11 x 11 x 9.5	0.148
Shielded inductor	Murata	1 mH @ 2.4A	29.8φ x 21.8	0.189



>1000x

- Capacitors have >1000x higher energy density than inductors
- Same holds with on-die scale devices/technology

Recent Work, Example 1: TM Andersen et al., ISSCC 2014



2:1 and 3:2 topology

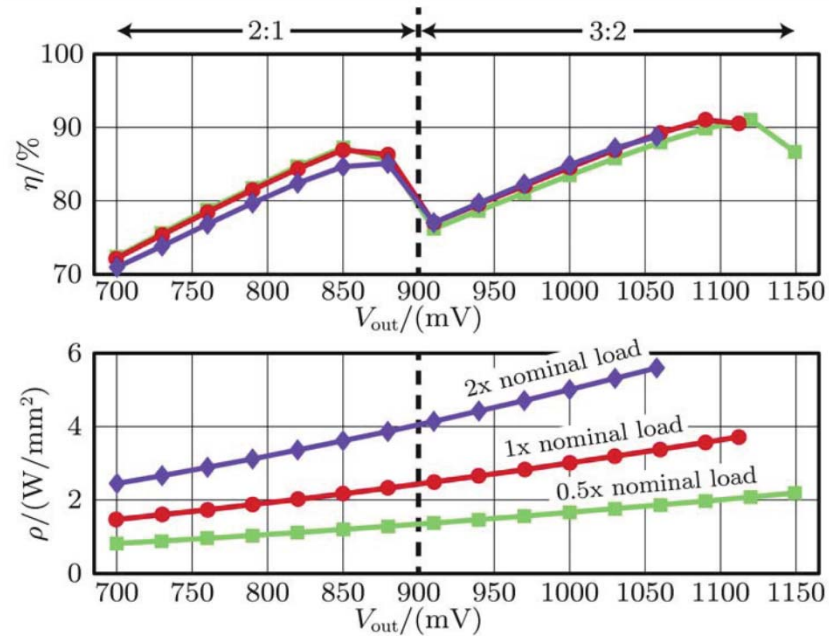
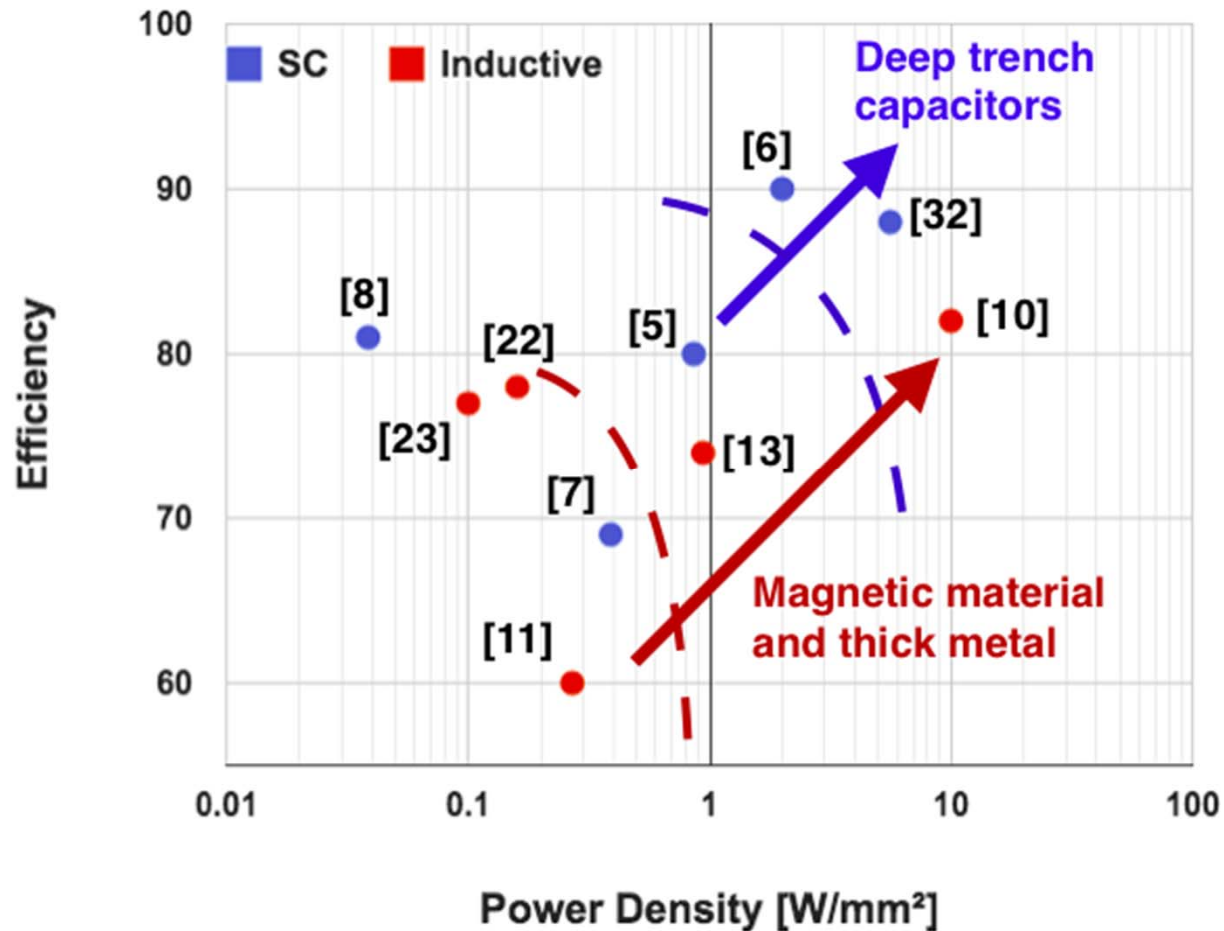


Figure 4.7.5: Measured efficiencies and power densities for $V_{in}=1.8V$ over the full output voltage range.

- ~290 nF/sq.mm deep trench cap
- 16 phase, with 125 MHz per phase
- ~6 W/sq.mm @ 88-89% eff

Performance with advanced passives



References in fig: [6] L. Chang, "A fully integrated switched capacitor ..." *VLSI*, 2010

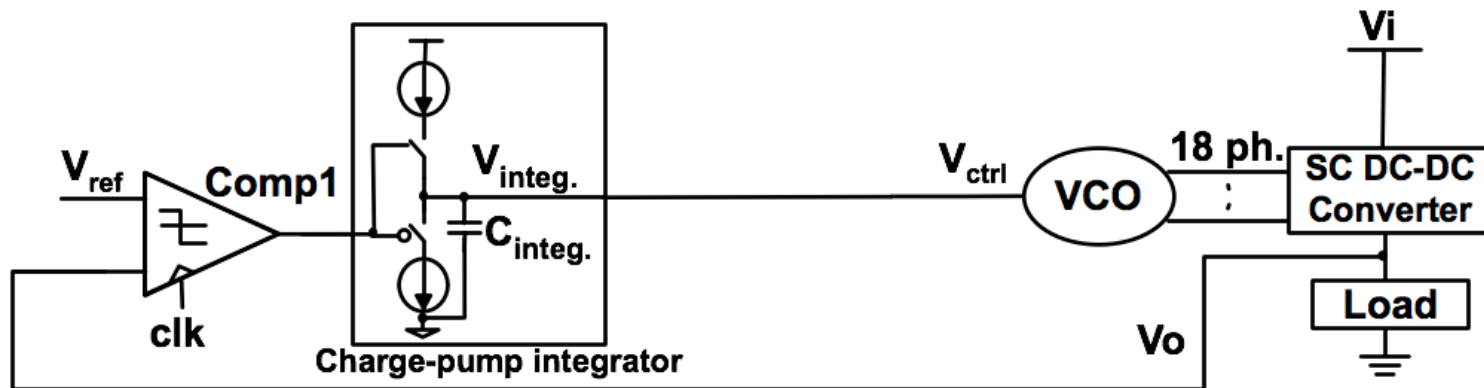
[5] HP Le, ISSCC 2010

[10] J. Dibene, "A 400A fully integrated silicon ..." *APEC*, 2010

[32] T.M. Anderson et al., ISSCC 2014

(Sanders et al., *IEEE T-PELS* 2013, "The Road to ...")

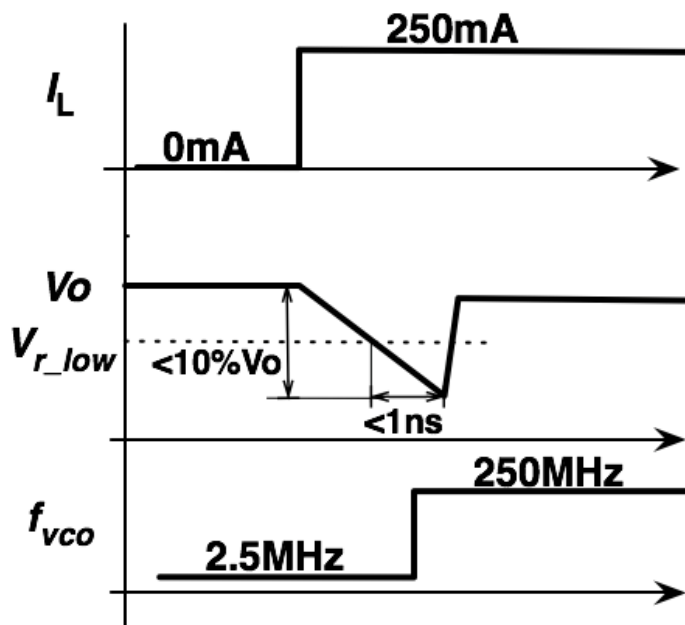
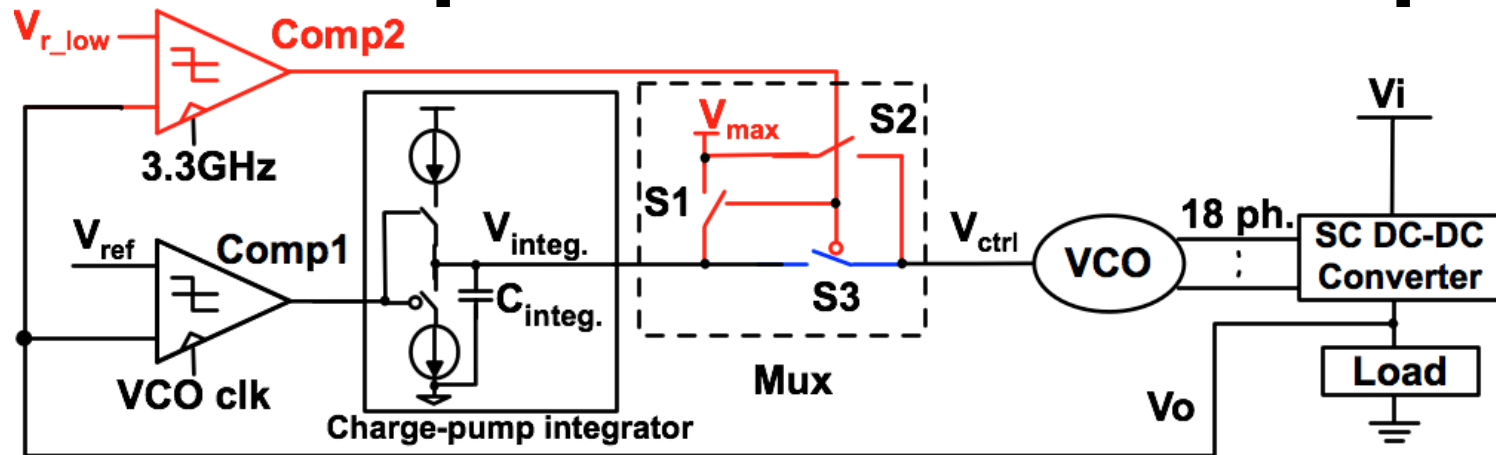
Simple Closed-Loop Control (Ex. 1 cont.)



- **Output impedance of the regulator set by f_{vco}**
 - $R_{out} \propto 1/(f_{vco} C_{fly})$
- **Switching frequency set by (slow) integral control loop**
- **Key challenge: response to $0 \rightarrow I_{max}$ load step**

(Ref: H-P Le et al, ISSCC 2013)

Control Loop with Fast Load Response



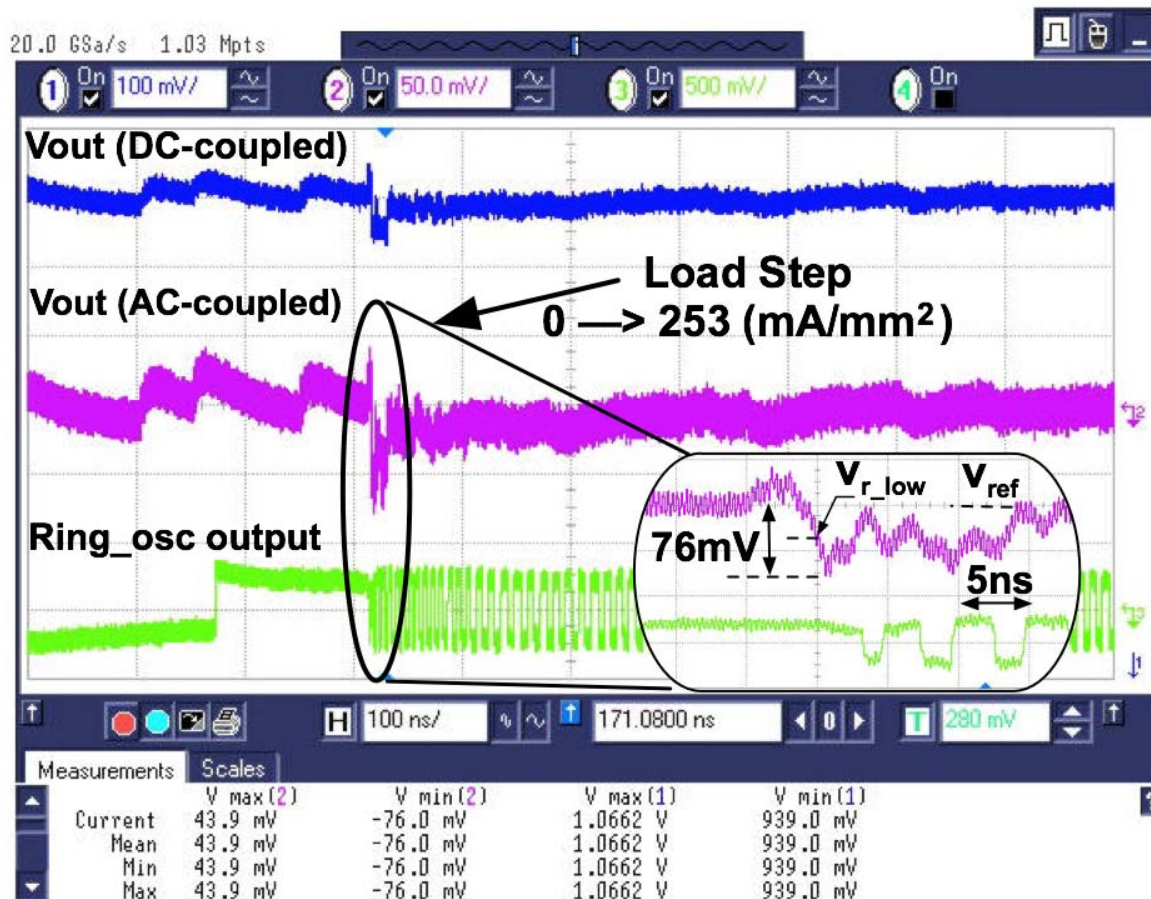
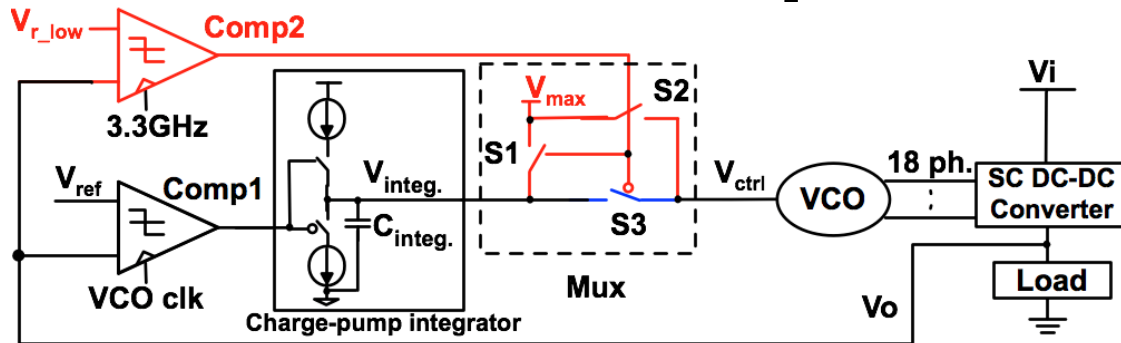
- Additional comparator “jumps” f_{vco}

- Need sub-ns response time for $<10\%$ droop

- Comparator must sample V_o at high frequency

(Ref: H-P Le et al, ISSCC 2013)

Load Step Measurement



- Load step generated by on-die load circuitry

- Achieves 7.6% droop under a full load step (50ps rise time) of 253mA/mm²

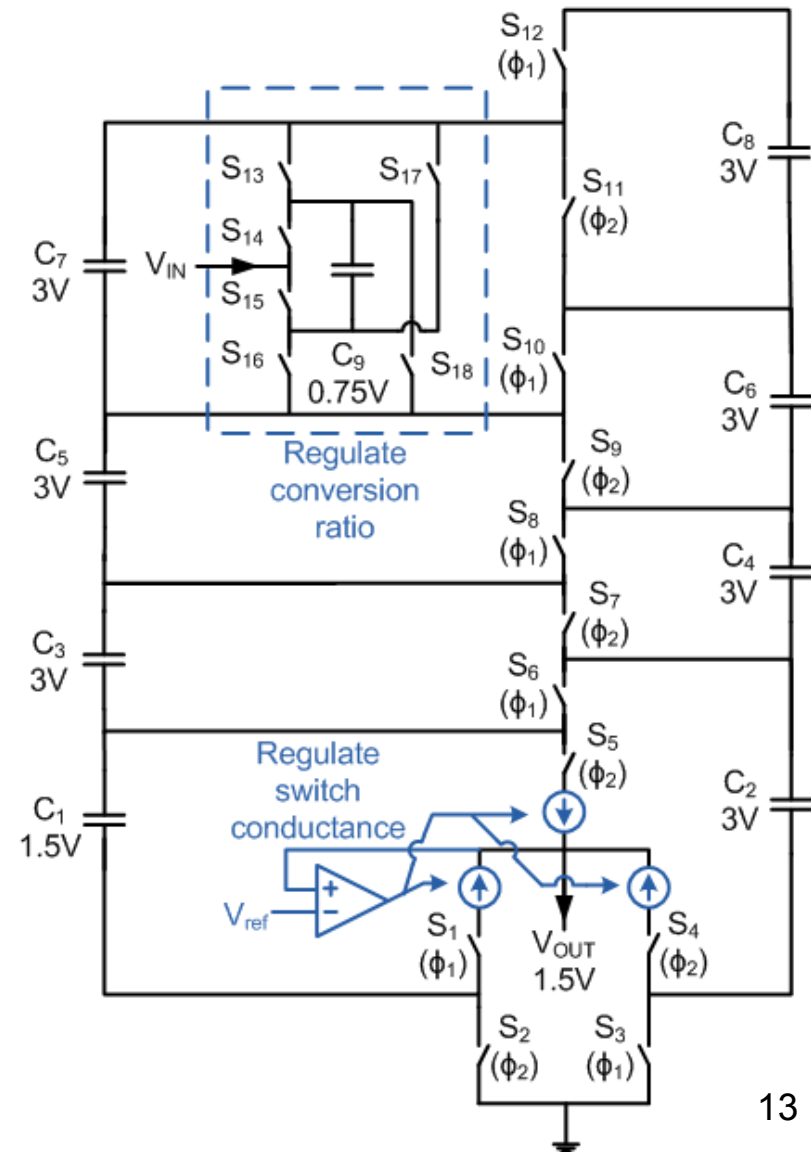
- Indicates response time of < 1ns

(Ref: H-P Le et al, ISSCC 2013)¹²

Example 2 – Point-of-Load:12V-to-1.5V Dickson Type Circuit

Illustrates “tap-changing” technique for line regulation.

- Dickson converter with nominal conversion ratios: 5-to-1, 5.5-to-1, ... , 8-to-1
- Modulate switch conductance for fine regulation
- Modulate switching frequency for high efficiency at light load
- Illustrates wide range conversion and voltage domain stacking



(Ref: V.W. NG et al, IEEE T-PELS 2013)

Transient measurement – load step

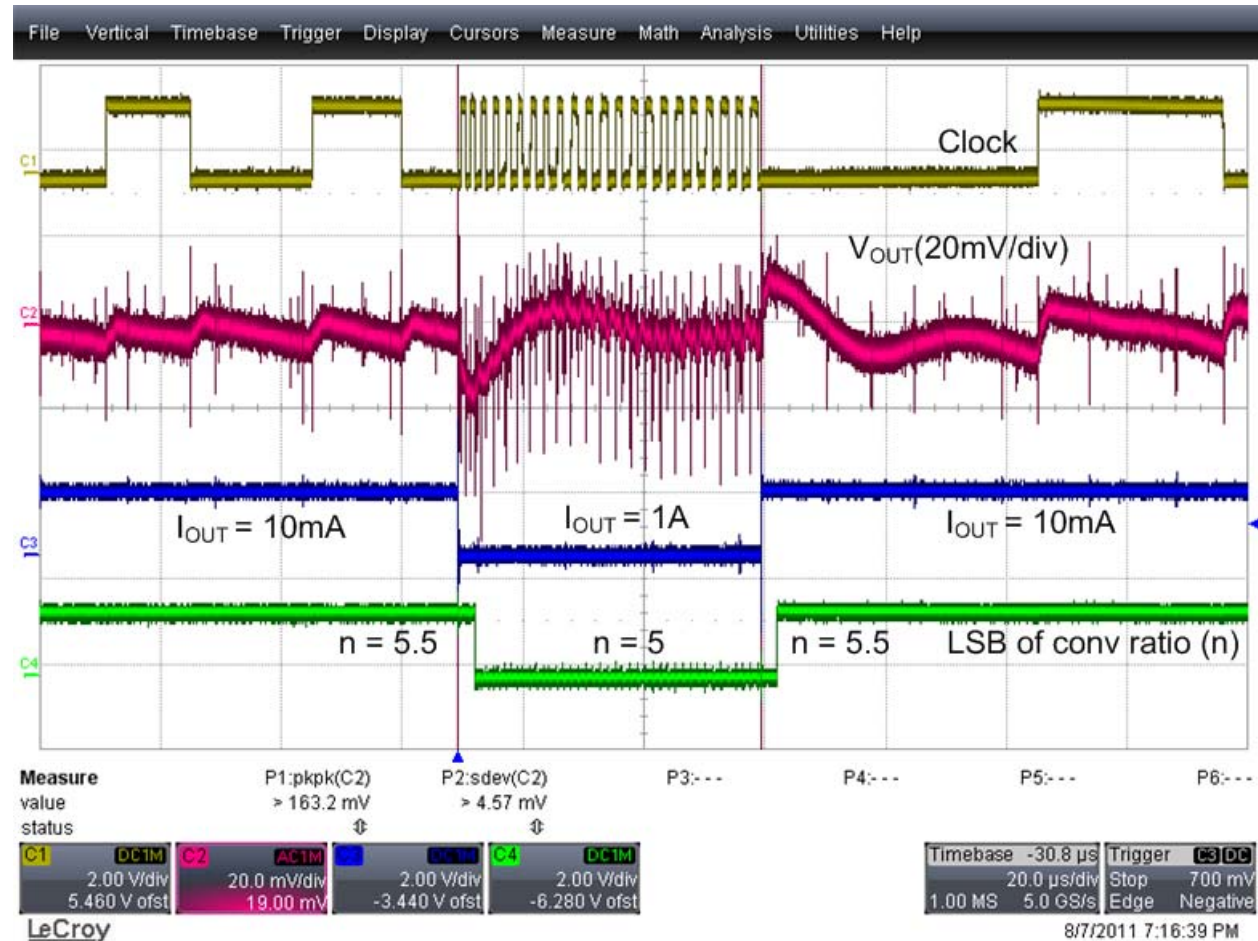
clock

V_{out}: 20 mV/div

Load Current:

10mA-1A-10mA

LSB (ratio)



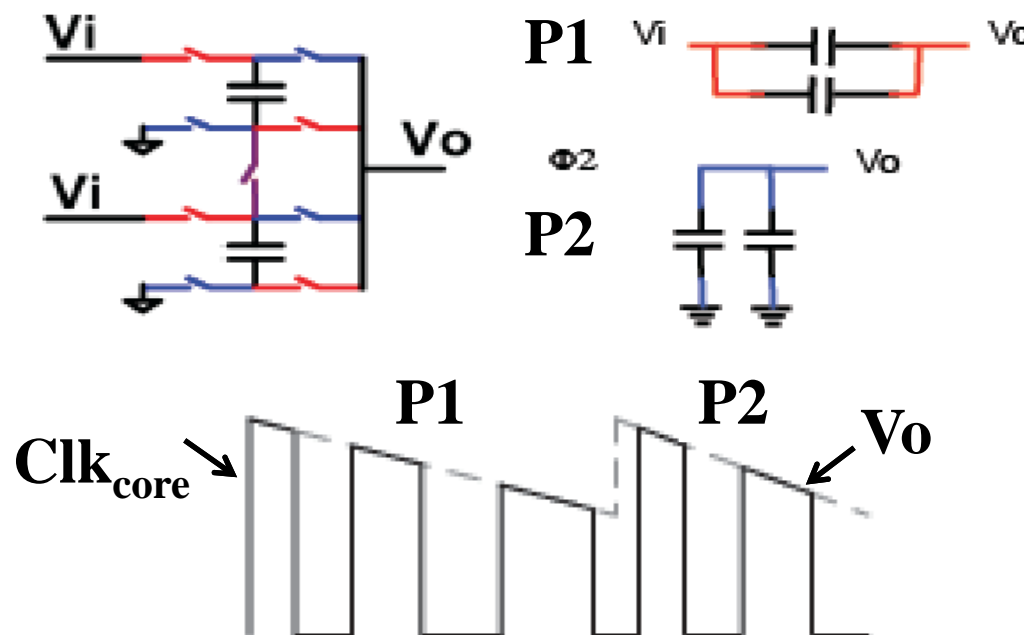
- V_{OUT} variation within 30mV during full loading and unloading transient
- C_{IN}=12 μ F, C_{OUT}=110 μ F, typical to 1A buck converters

(Ref: V.W. NG et al, IEEE T-PELS 2013)

Ex. 3: Raven Processor Project (2014)– BWRC (UC Berkeley), Alberto Puggelli poster

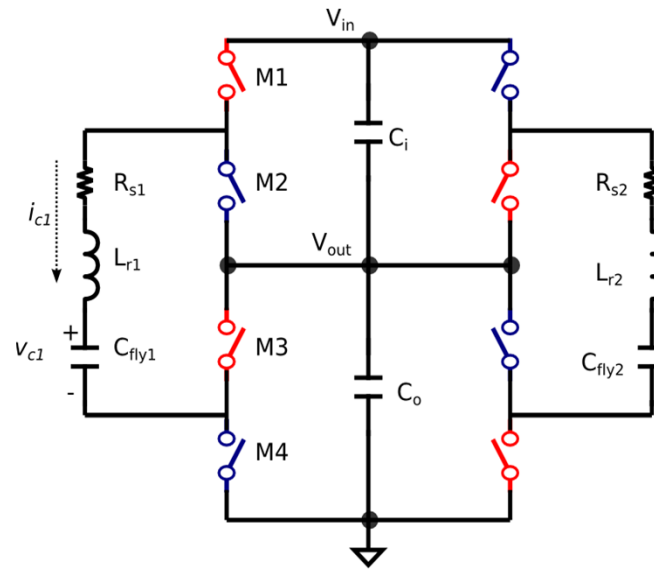
- Each digital unit is powered by a dedicated single-phase SC converter:
 - fine-grained DVFS
 - power gating
- Innovation: combine and exploit SC voltage ripple with DVS to adiabatically consume ripple energy

Basic unit cap cell and its functionality in 2:1



(Ref: IEEE T-VLSI 2014)

What's next? ResSC Topology(s)



Small on-die inductance resonates out working (flying) caps

- Avoid charge sharing losses
- Much larger swing on working caps, better use of valuable cap resources
- Net inductor V-A utilization superior to “conventional buck”, etc.
- Opportunities for lossless regulation
- Refs: Stauth et al. (ISSCC 2013,14), many others + on-going efforts

Related:

- “Soft charging” methods that adiabatically combine inductor-based and SC ckts
- Ex. Pilawa et al, IEEE PESC 2008

Why Not S-C ?

- Difficult regulation? **X**
- Interconnect difficulty for many caps? **X**
- Voltage rating of CMOS processes? **X**
- Magnetic-based ckts = higher performance? **X**
- Ripple? **X**
- Fundamental charge sharing losses? **X**